

**Invitation Letter**

**April 22, 2024**

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| Participant’s Full Name: |  |
| Name of the Organization: |  |
| Full Address: |  |
| Birth Date: |  |
| Passport Number: |  |
| Abstract No.: |  |

**Dear Mr. / Mrs.**

This is to certify that ( *Name* ) is the author of Paper ( *Abstract No.* ) ( *Paper Title* ) which was accepted to the 3rd World Congress on Condition Monitoring (WCCM) which will be held from October 15 - 18 2024 at Beijing International Convention Center, Beijing, China, and who is asked to make an in-person presentation during the conference.We believe that your participation will contribute a great deal to an enrichment of the 3rd WCCM.

The WCCM is the world’s biggest event in the field of CM, held every two years. The 3rd WCCM will provide a dynamic technical program which will be highly informative and instructive for every participant. Also, we, the Organizing Committee, are confident that the 3rd WCCM will turn out to be the most successful platform for networking and inspiring new technical ideas with the support from all of you.

All the expenses will be guaranteed by the participants.

Sincerely yours,

**Gongtian Shen**

*Chair of the 3rd WCCM*

*The President of Chinese Society for Non-destructive Testing*

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| **The 3rd WCCM Secretariat** |
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